

SLOVENSKI STANDARD

SIST EN IEC 60068-2-83:2025

01-oktober-2025

Nadomešča:

SIST EN 60068-2-83:2012

Okoljsko preskušanje - 2-83. del: Preskusi - Preskus tf: Preskus spajkanja elektronskih komponent za površinsko montažo (SMD) z metodo za ugotavljanje omočljivosti z uporabo spajkalne paste

Environmental testing - Part 2-83: Tests - Test tf: Solderability testing of electronic components for surface mounting devices (SMD) by the wetting balance method using solder paste

Umweltprüfungen – Teil 2-83: Prüfungen - Prüfung tf: Prüfung der Lötbarkeit von elektronischen Bauelementen für oberflächenmontierbaren Bauelementen (SMD) nach dem Benetzungsbilanzverfahren unter Verwendung von Lotpaste

Essais d'environnement - Partie 2-83: Essais - Essai tf: Essai de brasabilité des composants électroniques pour les composants pour montage en surface (CMS) par la méthode de la balance de mouillage utilisant de la pâte à braser

Ta slovenski standard je istoveten z: EN IEC 60068-2-83:2025

ICS:

19.040	Preskušanje v zvezi z okoljem	Environmental testing
31.190	Sestavljeni elektronski elementi	Electronic component assemblies

SIST EN IEC 60068-2-83:2025

en

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN IEC 60068-2-83

July 2025

ICS 19.040; 31.190

Supersedes EN 60068-2-83:2011

English Version

**Environmental testing - Part 2-83: Tests - Test Tf: Solderability
testing of electronic components for surface mounting devices
(SMD) by the wetting balance method using solder paste
(IEC 60068-2-83:2025)**

Essais d'environnement - Partie 2-83: Essais - Essai Tf:
Essai de brasabilité des composants électroniques pour les
composants montés en surface (CMS) par la méthode de la
balance de mouillage utilisant de la pâte à braser
(IEC 60068-2-83:2025)

Umweltprüfungen - Teil 2-83: Prüfungen - Prüfung Tf:
Prüfung der Lötbarkeit von elektronischen Bauelementen
für oberflächenmontierbaren Bauelementen (SMD) nach
dem Benetzungsbilanzverfahren unter Verwendung von
Lotpaste
(IEC 60068-2-83:2025)

This European Standard was approved by CENELEC on 2025-07-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Croatia, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Republic of North Macedonia, Romania, Serbia, Slovakia, Slovenia, Spain, Sweden, Switzerland, Türkiye and the United Kingdom.



European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 60068-2-83:2025 (E)**European foreword**

The text of document 91/2026/FDIS, future edition 2 of IEC 60068-2-83, prepared by TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60068-2-83:2025.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2026-07-31 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2028-07-31 document have to be withdrawn

This document supersedes EN 60068-2-83:2011 and all of its amendments and corrigenda (if any).

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Any feedback and questions on this document should be directed to the users' national committee. A complete listing of these bodies can be found on the CENELEC website.

Endorsement notice

The text of the International Standard IEC 60068-2-83:2025 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 60068-2-69 NOTE Approved as EN 60068-2-69

IEC 60068-3-13:2016 NOTE Approved as EN 60068-3-13:2016 (not modified)

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-20	2021	Environmental testing - Part 2-20: Tests - Test Ta and Tb: Test methods for solderability and resistance to soldering heat of devices with leads	EN IEC 60068-2-20	2021
IEC 60068-2-58	-	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	-
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications	EN IEC 61190-1-3	-

